

201210US-2 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF : :

OSAMU FURUKAWA, ET AL. : GROUP UNIT:

SERIAL NO: NEW DIV. APPLN. : :

FILED: HEREWITH : EXAMINER:

FOR: ELECTRONIC COMPONENT AND :
METHOD OF PRODUCTION THEREOF

*H. R. Brinkley
C. J. Gibson
7-20-05*

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

SIR:

Prior to initial examination on the merits, please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel Claims 1-165 without prejudice or disclaimer.

Please add new Claims 166-171 as follows:

SUP B1
--166. A surface acoustic wave device, comprising:

a printed circuit board possessing a first board surface and a second board surface, the first board surface having a board wiring pattern and a board wiring pad which is thicker than the board wiring pattern;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, an element wiring pad, and a surface acoustic wave absorbing member formed outside of the element wiring pad, and the first element surface being disposed in an opposite relation with respect to the first board surface; and